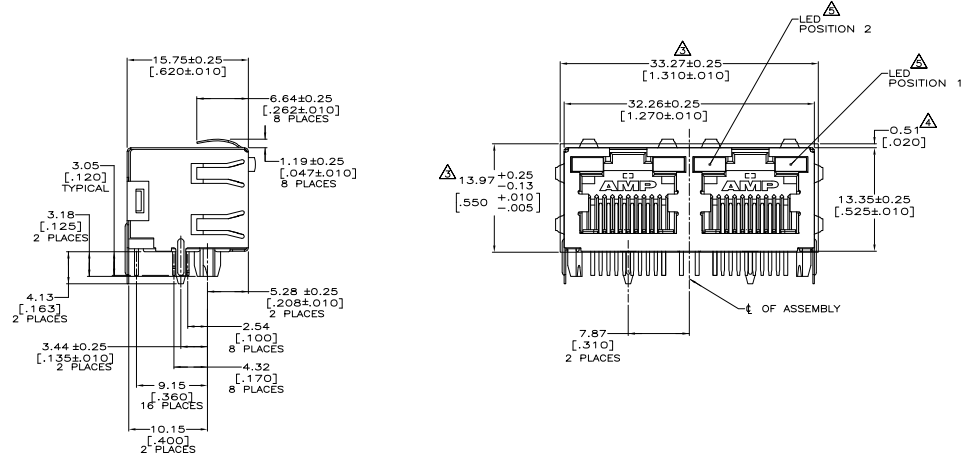
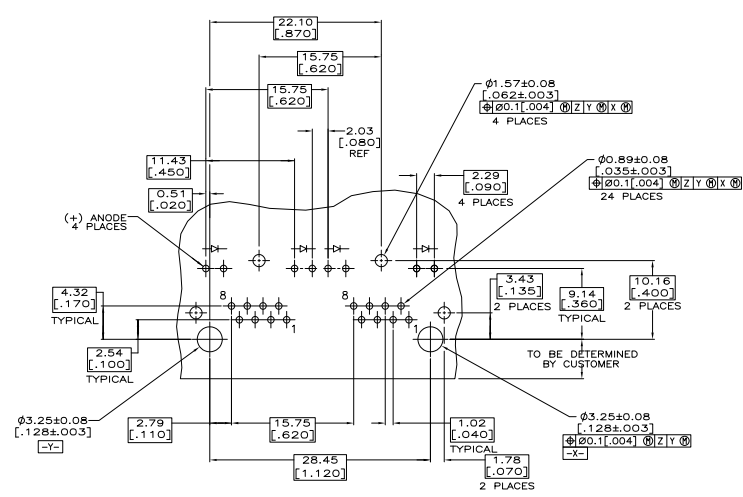


REV	DATE	DESCRIPTION	BY	CHK	APP
AA	22				
A		REV PER EC 0511-0201-04			



- △ MATERIAL:
 HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0.
 TERMINALS - 0.36[.014] THICK PHOS BRONZE PLATED WITH 3.81µm[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA, 1.27µm [0.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm [0.000050] MINIMUM THICK NICKEL.
 SHIELD - 0.196[.0077] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27µm[0.000050] MINIMUM SATIN NICKEL WITH 2.03µm[0.000080] MINIMUM TIN POST DIPPED ON PCB GROUND TABS.
 LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS, 0.51 x 0.51[.020 x .020] CARBON STEEL WIREFRAME LEADS PREPLATED WITH 8.89 µm[.0003500] THICK Sn/Cu OVER 2.03 µm[.000080] THICK Ag OVER 1.02µm[.000040] THICK Cu OVER 3.56 µm[.000140] THICK Ni OVER 1.02µm[.000040] Cu UNDERPLATE
- JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
 - SUGGESTED PANEL OPENING DIMENSIONS.
 - SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.
 - SEE TABLE FOR COLOR OF LEDS AND NUMBER REQUIRED.
 - THIS MODULAR JACK WITH INTEGRATED LED IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT
 (COMPONENT SIDE)

POSITION 2	POSITION 1	PART NUMBER
GREEN	YELLOW	6368460-4
INDICATOR COLOR FOR EACH HOUSING		

THIS DRAWING IS A CONTROLLED DOCUMENT		TYSO ELECTRONICS CORPORATION Harrisburg, PA 17105-3608	
DATE	REV	DESCRIPTION	REV
108-1163-4	1	INVERTED MODULAR JACK ASSEMBLY, (XZ, SHIELDED), PANEL GROUND, WITH LEADS	
114-2154			
CUSTOMER DRAWING		REV	REV
		4.1	1